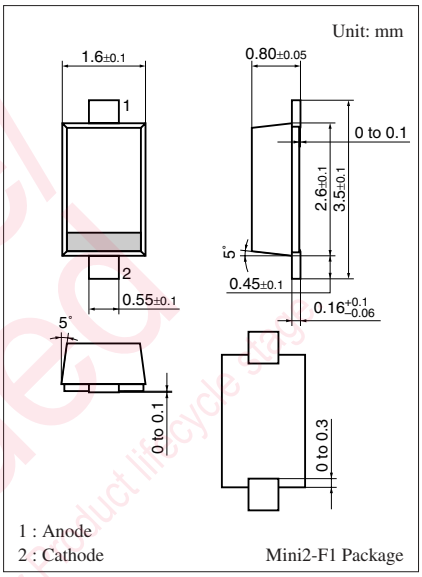
MA2YD23

Silicon epitaxial planar type

For high frequency rectification



Marking Symbol: 2W

■ Features

- Forward current (Average) $I_{F(AV)}$ = 1 A rectification is possible
- Low forward voltage V_F
- Small reverse current I_R

■ Absolute Maximum Ratings T_a = 25°C

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	25	V
Repetitive peak reverse voltage	V_{RRM}	25	V
Forward current (Average) *1	$I_{F(AV)}$	1.0	A
Non-repetitive peak forward surge current *2	I_{FSM}	3	A
Junction temperature	T_j	125	°C
Storage temperature	T_{stg}	−55 to +125	°C

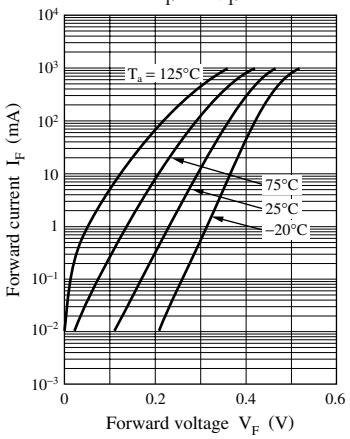
Note) ∗1: Mounted on an alumina PC board
∗2: The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)

■ Electrical Characteristics T_a = 25°C ± 3°C

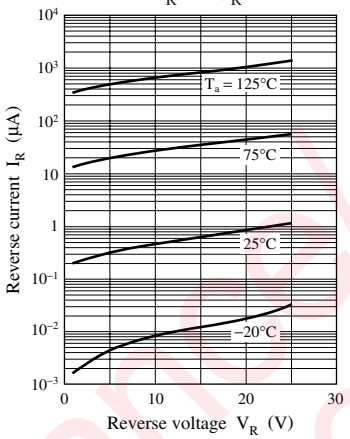
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_{F1}	I_F = 0.5 A		0.42	0.47	V
	V_{F2}	I_F = 1.0 A		0.46	0.55	
Reverse current	I_{R1}	V_R = 15 V		1.5	20.0	µA
	I_{R2}	V_R = 20 V		2.5	40.0	

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

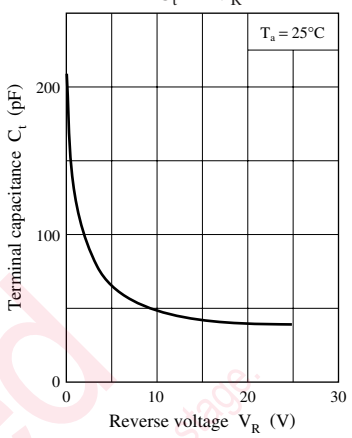
I_F — V_F



I_R — V_R



C_t — V_R



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Even when the products are used within the guaranteed values, take into the consideration of incidence of break down and failure mode, possible to occur to semiconductor products. Measures on the systems such as redundant design, arresting the spread of fire or preventing glitch are recommended in order to prevent physical injury, fire, social damages, for example, by using the products.

(6) Comply with the instructions for use in order to prevent breakdown and characteristics change due to external factors (ESD, EOS, thermal stress and mechanical stress) at the time of handling, mounting or at customer's process. When using products for which damp-proof packing is required, satisfy the conditions, such as shelf life and the elapsed time since first opening the packages.